

10/586675

IAP6 Rec'd PCT/PTO 20 JUL 2006

DOCKET NO.: 288839US0PCT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Ekkehard MUEH, et al.

SERIAL NO.: NEW U.S. PCT APPLICATION

FILED: HEREWITH

INTERNATIONAL APPLICATION NO.: PCT/EP04/53669

INTERNATIONAL FILING DATE: December 22, 2004

FOR: SILICON COMPOUNDS FOR PRODUCING SIO₂-CONTAINING INSULATING
LAYERS ON CHIPS

REQUEST FOR PRIORITY UNDER 35 U.S.C. 119
AND THE INTERNATIONAL CONVENTION

Commissioner for Patents
Alexandria, Virginia 22313

Sir:

In the matter of the above-identified application for patent, notice is hereby given that
the applicant claims as priority:

<u>COUNTRY</u>	<u>APPLICATION NO</u>	<u>DAY/MONTH/YEAR</u>
Germany	10 2004 008 442.4	19 February 2004

Certified copies of the corresponding Convention application(s) were submitted to the
International Bureau in PCT Application No. PCT/EP04/53669. Receipt of the certified
copy(s) by the International Bureau in a timely manner under PCT Rule 17.1(a) has been
acknowledged as evidenced by the attached PCT/IB/304.

Respectfully submitted,
OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.



Norman F. Oblon
Attorney of Record
Registration No. 24,618
Surinder Sachar
Registration No. 34,423

Customer Number

22850

(703) 413-3000
Fax No. (703) 413-2220
(OSMMN 08/03)